

ABSTRACT OF THE DISCLOSURE

A lead frame that does not have tie straps and a die bond pad is rectangular in shape, with the same number of lead frame leads(11) on opposite sides and a different number of lead frame lead frame leads (11) on adjacent sides. Lead frame leads (11) extend into the area in which the tie strap would normally be placed. A heat slug is (30) taped to the lead frame to provide a semiconductor die mount area. At least one lead (11) from one side of the lead frame, located where the tie strap is normally located, is connected via a bond wire (17a,17b) to a bond pad (19) on the semiconductor die (18) on a side adjacent to the side where the lead frame lead is located.